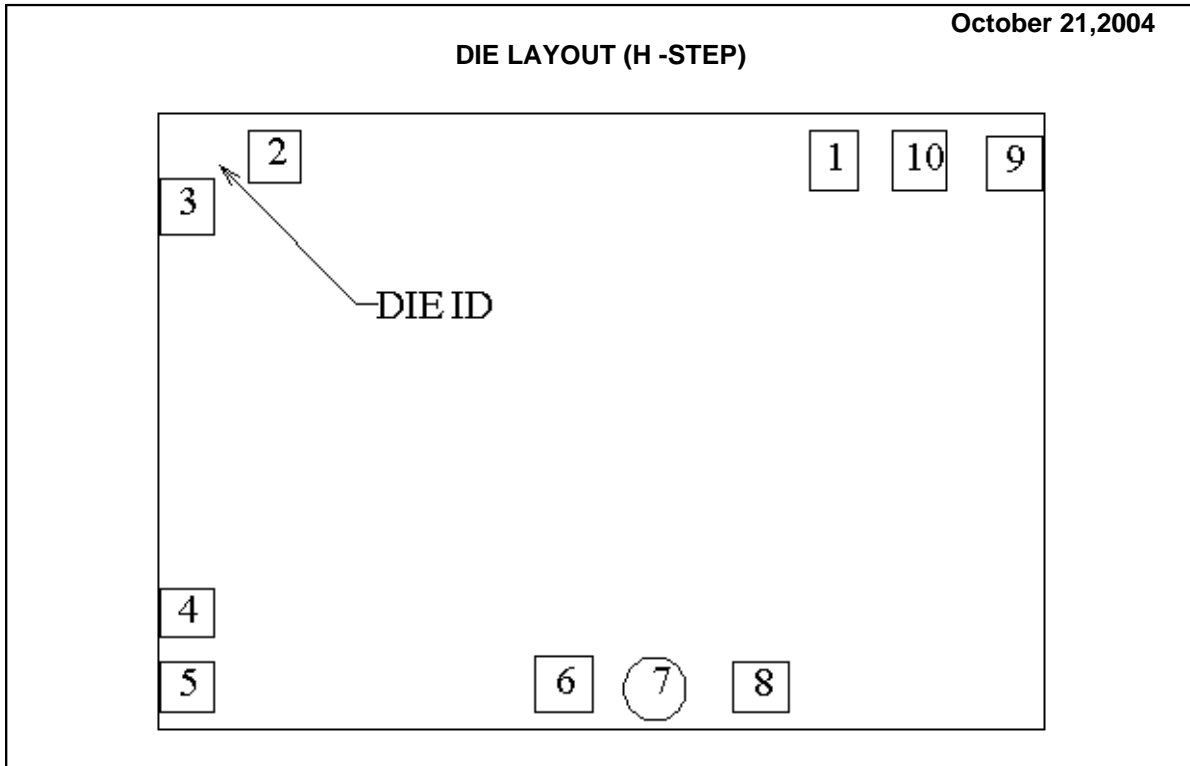


LM111 MD8 MCD2000A
VOLTAGE COMPARATOR



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	111H	Bond Pad Opening Size (min)	91 μ m x 112 μ m
Die Step	H	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1651 μ m x 1143 μ m 65.0mils x 45.0mils	Back Side Connection	Floating
Thickness	330 μ m Nominal		
Min Pitch	140 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (H -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
GND	1	434	485	91	x	112
INPUT+	2	-607	493	97	x	97
INPUT-	3	-771	400	99	x	104
V-	4	-771	-356	99	x	91
Balance	5	-771	-495	99	x	91
Balance/Strobe	6	-69	-489	107	x	104
NC	7	114	-483	117	x	117
NC	8	298	-495	104	x	91
Output	9	768	479	104	x	99
V+	10	593	485	99	x	112

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K

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